



# P/N 97-68340 for Motorola 68340 144-Pin QFP-to-PGA Adapter

## FEATURES

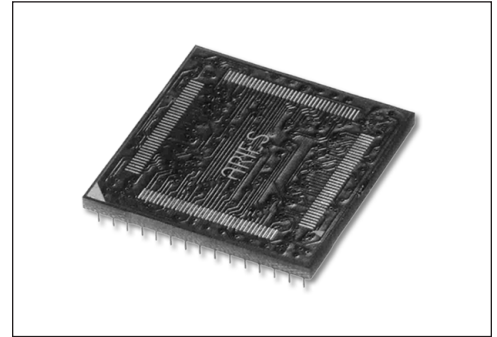
- Convert surface mount QFP packages to a 15x15 PGA footprint
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact
- Consult factory for panelized form or for mounting of consigned chips

## GENERAL SPECIFICATIONS

- ADAPTER BODY: FR-4, 0.062 [1.58] thick, with 1-oz. min. Cu traces
- PADS: bare Cu protected with ENIG or immersion white Sn to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000 ASTM-B16-00
- PIN PLATING: 200 $\mu$  [5.08 $\mu$ ] min. Sn per ASTM B 545 Type 1 or Sn/Pb 93/7 per ASTM B 545 over 100 $\mu$  [2.54 $\mu$ ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

## MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.062  $\pm$  0.003 [1.58  $\pm$  0.08] dia.
- Will plug into standard PGA sockets



**CUSTOMIZATION:** In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

## ORDERING INFORMATION

P/N 97-68340

P/N 97-68340-P for Panelized Form

P/N 145-PGM15024-30 for Wire Wrap PGA Socket

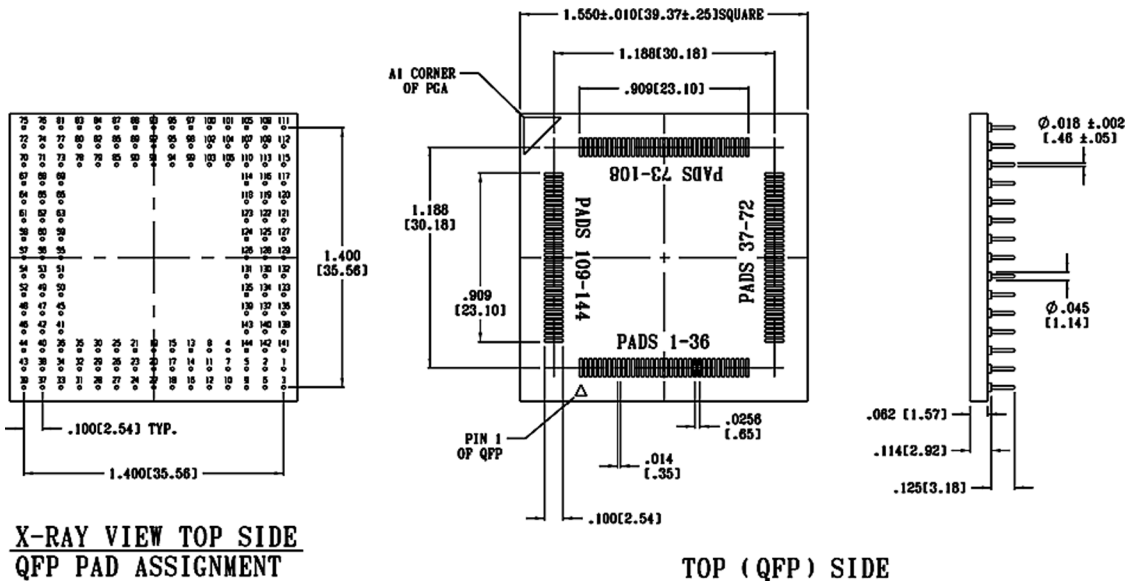
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES:  $\pm$ 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW  $\pm$ 0.003 [ $\pm$ 0.08]

PIN-TO-PIN  $\pm$ 0.003 [ $\pm$ 0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



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